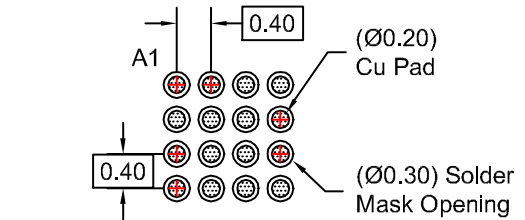
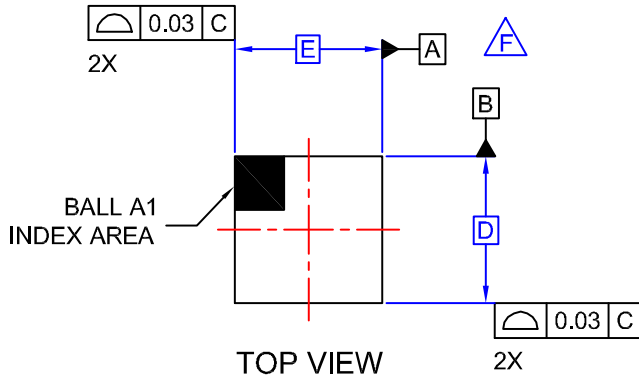
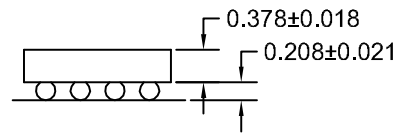
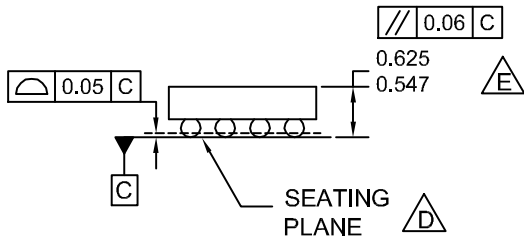


**WLCSP16 1.96x1.76x0.586**  
CASE 567SE  
ISSUE O

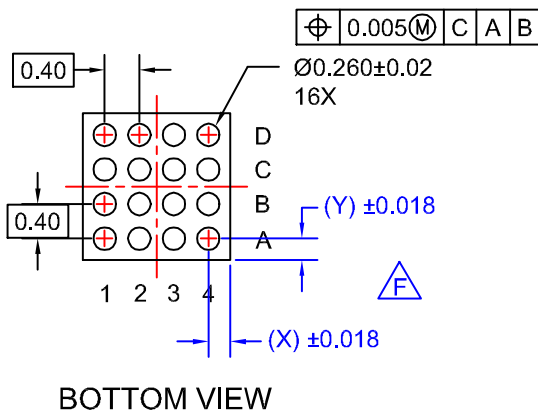
DATE 30 NOV 2016



**RECOMMENDED LAND PATTERN**  
(NSMD PAD TYPE)



**SIDE VIEWS**



**BOTTOM VIEW**

**NOTES:**

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASME Y14.5M, 1994.
- D** DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E** PACKAGE NOMINAL HEIGHT IS 586 MICRONS ±39 MICRONS (547-625 MICRONS).
- F** FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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<b>STATUS:</b>	<b>ON SEMICONDUCTOR STANDARD</b>	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	<b>WLCSP16 1.96x1.76x0.586</b>	<b>PAGE 1 OF 2</b>

